

/ Descriptions

SOT-23 PNP Silicon PNP transistor in a SOT-23 Plastic Package.

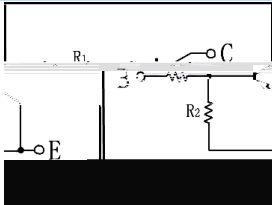
/ Features

With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process.

/ Applications

Switching, inverter circuit, interface circuit and driver circuit applications.

/ Equivalent Circuit



/ Pinning



PIN 1 Base PIN 2 Emitter PIN 3 Collector

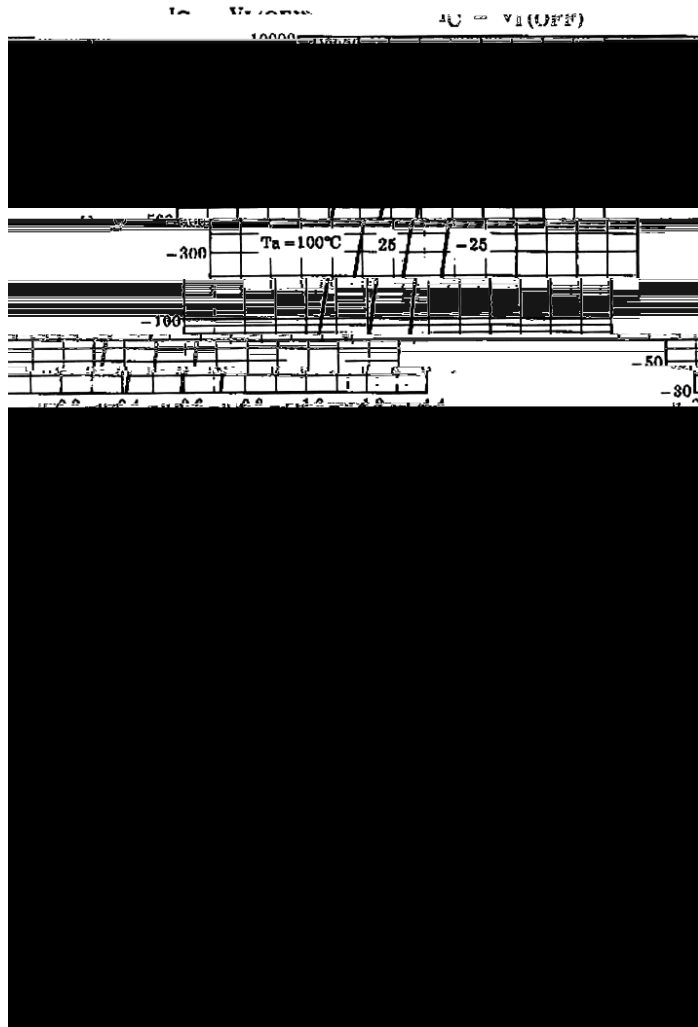
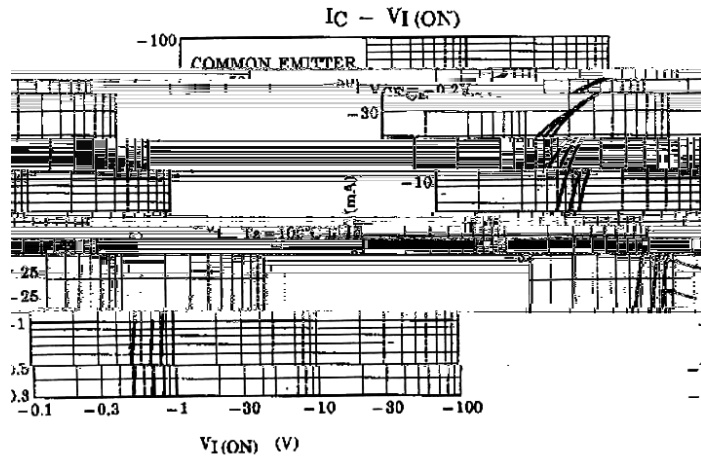
/ h_{FE} Classifications & Marking

h _{FE} Range	>80
Marking	HE32

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-50	V
Collector to Emitter Voltage	V_{CEO}	-50	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current	I_C	-100	mA
Collector Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	
Storage Temperature Range	T_{stg}	-55 150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage	$V_{I(ON)}$	$V_{CE}=-0.2V$ $I_C=-5.0mA$	-0.6		-1.1	V
Input Voltage	$V_{I(OFF)}$	$V_{CE}=-5.0V$ $I_C=-0.1mA$	-0.5		-0.8	V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-50V$ $I_E=0$			-0.1	μA
Collector Cut-Off Current	I_{CEO}	$V_{CE}=-50V$ $I_B=0$			-0.5	μA
Emitter Cut-Off Current	I_{EBO}	$V_{EB}=-5.0V$ $I_C=0$	-0.078		-0.145	mA
DC Current Gain	h_{FE}	$V_{CE}=-5.0V$ $I_C=-10mA$	80			
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=-5.0mA$ $I_B=-0.25mA$		-0.1	-0.3	V
Transition Frequency	f_T	$V_{CE}=-10V$ $I_C=-5.0mA$		200		MHz
Collector Output Capacitance	C_{ob}	$V_{CB}=-10V$ $I_E=0mA$ $f=1.0MHz$		3.0	6.0	pF
Input Resistor	R_1		1.54	2.2	2.86	K
Resistor ratio	R_2/R_1		19.4	21	23.7	

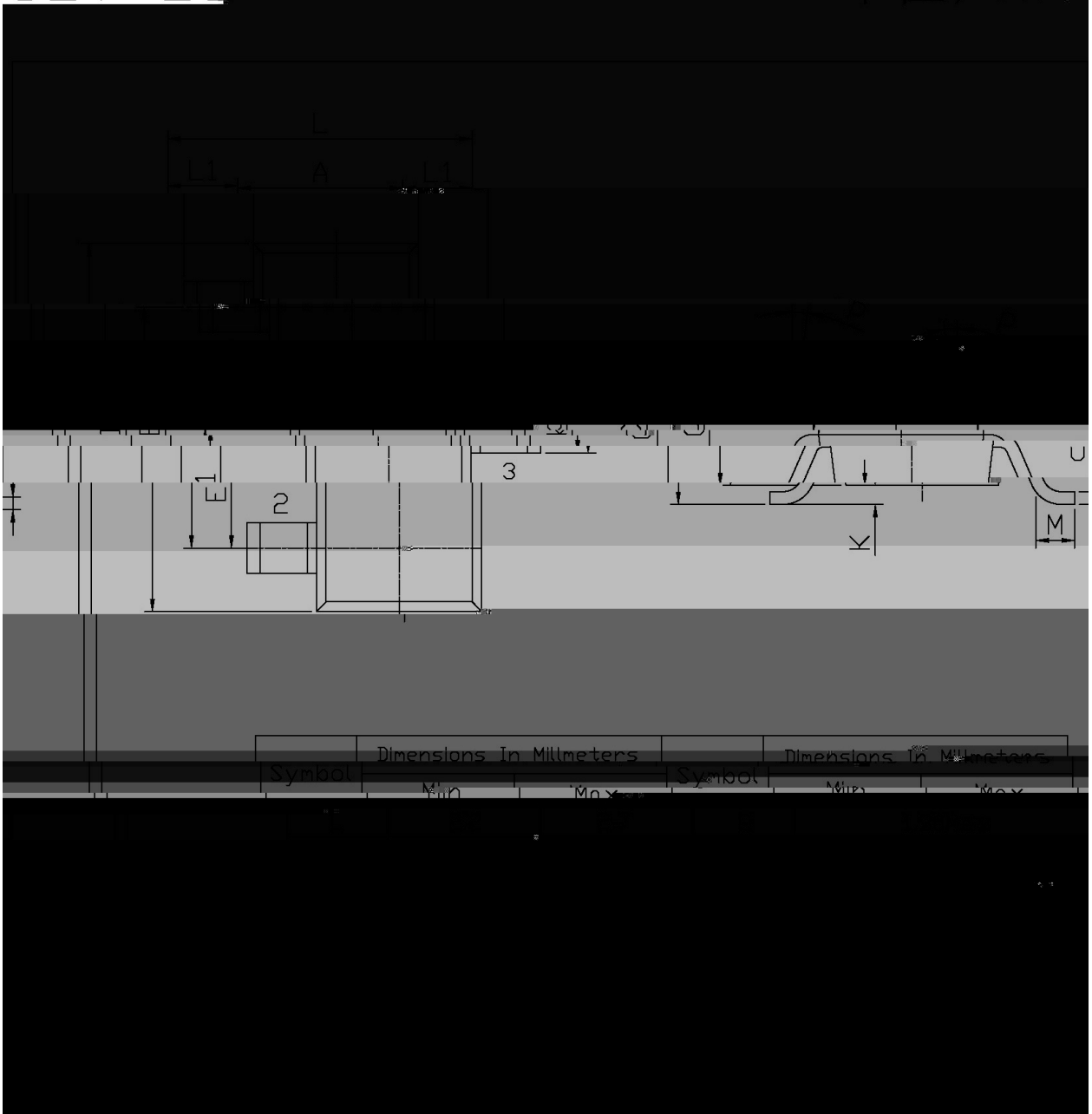
/ Electrical Characteristic Curve



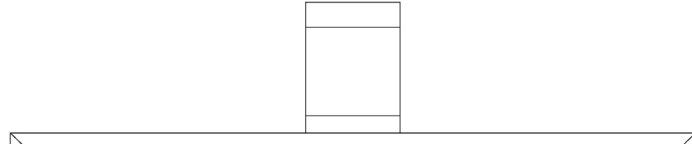
/ Package Dimensions

SOT-23

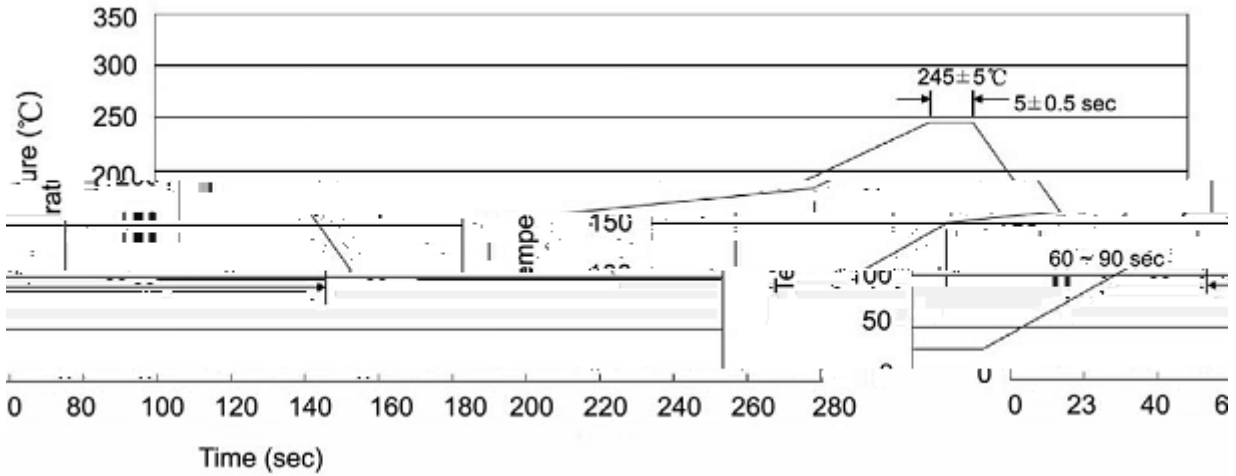
单位: mm



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|---|
| 1 | 25 | 150 | 60 | 90sec; | 1.Preheating:25~150 , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | | 2 | 10 /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱